

09/269316

Practitioner's Docket No. GD7000PCT(US)

PATENT

**TRANSMITTAL LETTER TO THE U.S. DESIGNATED OFFICE (DO/US)--  
ENTRY INTO THE U.S. NATIONAL STAGE UNDER CHAPTER I**

PCT/US98/23545	04 November 1998 (4.11.98)	04 November 1998 (4.11.98)
International Application Number	International Filing Date	International Earliest Priority Date

TITLE OF INVENTION: **COMPONENT OF PRINTED CIRCUIT BOARDS**APPLICANT(S) FOR DO/US: **GA-TEK Inc. (dba Gould Electronics Inc.); SCHNEIDER, Bernd**

**Box PCT  
Assistant Commissioner for Patents  
Washington D.C. 20231**

**ATTENTION: DO/US**

1. Applicant herewith submits to the United States Designated Office (DO/US) the following items under 35 U.S.C. § 371:

An express request to immediately begin national examination procedures (35 U.S.C. 371(f)).

**CERTIFICATION UNDER 37 C.F.R. 1.10\****(Express Mail label number is mandatory.)**(Express Mail certification is optional.)*

I hereby certify that this paper, along with any document referred to, is being deposited with the United States Postal Service on this date **March 24, 1999** in an envelope as Express Mail Post Office to Addressee," mailing Label Number **EE294565865US**, addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231.

Elaine Zakrzewski*(type or print name of person mailing paper)*
*Signature of person mailing paper*

**WARNING:** Certificate of mailing (first class) or facsimile transmission procedures of 37 C.F.R 1.8 cannot be used to obtain a date of mailing or transmission for this correspondence.

**\*WARNING:** Each paper or fee filed by "Express Mail" **must** have the number of the "Express Mail" mailing label placed thereon prior to mailing. 37 C.F.R 1.10(b).

"Since the filing of correspondence under § 1 10 without the Express Mail mailing label thereon is an oversight that can be avoided by the exercise of reasonable care, requests for waiver of this requirement will **not** be granted on petition." Notice of Oct. 24, 1996, 60 Fed Reg. 56,439, at 56,442.

The U.S. National Fee (U.S.C. § 371(c)(1)) and other fees (37 C.F.R. § 1.492), as indicated below:

2. Fees

CLAIMS FEE*	(1) FOR	(2) NUMBER FILED	(3) NUMBER EXTRA	(4) RATE	(5) CALCULATIONS
	TOTAL CLAIMS	12 -20 =	0	x \$18.00 =	\$0.00
	INDEPENDENT CLAIMS	2 - 3 =	0	x \$78.00 =	\$0.00
	MULTIPLE DEPENDENT CLAIM(S) (if applicable) + \$260				
BASIC FEE	The international search fee, as set forth in § 1.445(a)(2) to be paid to the US PTO acting as an international Searching Authority:  has been paid (37 CFR 1.492(a)(2)) ..... \$760.00				
SMALL ENTITY	Total of above Calculations				
	= \$760.00				
	Reduction by ½ for filing by small entity, if applicable. Affidavit must be filed (note 37 CFR 1.9, 1.27, 1.28).				
	Subtotal				
	\$760.00				
	Total National Fee				
	\$760.00				
	Fee for recording the enclosed assignment document \$40.00 (37 CFR 1.21(h)). (See Item below). See attached "ASSIGNMENT COVER SHEET".				
TOTAL	Total Fees enclosed				
	\$800.00				

A check in the amount of \$800.00 to cover the above fees is enclosed.

3. A copy of the International application as filed (35 U.S.C. § 371(c)(2)) is not required, as the application was filed with the United States Receiving Office.
4. A translation of the International application into the English language (35 U.S.C. § 371(c)(2)) is not required as the application was filed in English.
5. An oath or declaration, including power of attorney, of the inventor (35 U.S.C. § 371(c)(4)) complying with 35 U.S.C. § 115 is submitted herewith, and such oath or declaration is attached to application.

Other document(s) or information included:

6. An international Search Report or Declaration under PCT Article 17(2)(a) is not transmitted, as the international search has not yet issued.

7. An Information Disclosure Statement under 37 C.F.R. §§ 1.97 and 1.98 is transmitted herewith. Also transmitted herewith is (are) Form PTO-1449 (PTO/SB/08A and 08B), and copies of citations listed.
8. An assignment document is transmitted herewith for recording. A separate "COVER SHEET FOR ASSIGNMENT (DOCUMENT) ACCOMPANYING NEW PATENT APPLICATION" is also attached. Please mail the recorded assignment document to the person whose signature and address appears below.
9. The above items are being transmitted before the 18th month publication.

#### **AUTHORIZATION TO CHARGE ADDITIONAL FEES**

10. The Commissioner is hereby authorized to charge the following additional fees that may be required by this paper and during the entire pendency of this application to Account No. 50-0537.

37 C.F.R. 1.492(a)(1), (2), (3), and (4) (filing fees)  
37 C.F.R. 1.492(b), (c), and (d) (presentation of extra claims)  
37 C.F.R. 1.17 (application processing fees)

Date: 24 MARCH 1999



Mark Kusner  
SIGNATURE OF PRACTITIONER

Reg. No. 31,115

Mark Kusner

Tel. No.: (440) 684-1090

Mark Kusner Co., LPA  
Highland Place - Suite 310  
6151 Wilson Mills Road  
Highland Heights, OH 44143

Customer Number 22203

PTO/PCT Rec'd 24 MAR 1999

09/269316

COMPONENT OF PRINTED CIRCUIT BOARDSField of the Invention

The present invention relates generally to printed circuits, and more particularly, to components used in the manufacturing of printed circuit boards and other articles.

Background of the Invention

In the manufacture of printed circuit boards, sheets of copper foil are typically bonded to a dielectric layer of a partially cured epoxy resin containing woven glass fiber (such a dielectric layer is conventionally referred to as a "pre-preg"). In the manufacture of copper clad laminates, sheets of copper foil are typically bonded to another layer of foil. In both processes, the copper foil is etched to produce conductive paths. In such processes, it is extremely important to avoid contamination of the copper foil sheets in that any foreign matter contacting the copper foil, such as resin dust, fiberglass fibers, hair, grease, oil or the like, may result in dots, dents, deposits or pits on the copper foil that can adversely affect the formation of the conductive paths forming the printed circuits.

Copper foil is conventionally formed by an electrodeposition process. Following the production of the copper foil, it is known to secure a metallic substrate to one side of the copper foil to protect that side of the copper foil from contamination during subsequent handling and shipping. The protected side of the copper foil is typically the side used to form the conductive pathways, while the exposed side of the foil is typically the side that is attached to a pre-preg or bonded to another layer of copper foil. The protective metallic substrate remains attached to the copper foil as it is attached to the pre-preg or bonded to the other layer of copper foil. The protective metallic substrate is subsequently removed and discarded (or recycled) to expose the protected, uncontaminated side of the foil for processing to form the conductive pathways.

U.S. Patent No. 5,153,050 to Johnston discloses a copper/aluminum/copper laminate wherein the shiny side of a copper foil is bonded along its peripheral edges to an aluminum substrate. U.S. Patent No. 5,674,596 to Johnston further discloses securing copper foil to a metallic substrate, such as a steel or a stainless steel substrate. U.S. Patent No. 5,512,381 to Konicek et al. discloses securing copper foil to a copper substrate.

Each of the foregoing structures uses a relatively expensive material, e.g., aluminum, stainless steel and copper, to form the disposable, protective substrate. In addition to the cost of such materials, copper and aluminum are relatively soft metals that are susceptible to image transfer during lamination of multi-layer laminates, 5 particularly at high lamination temperatures and pressures. Stainless steel is a stronger metal than copper or aluminum, and possesses the corrosion resistance necessary to avoid contamination of the copper foil sheet. As a result, stainless steel finds advantageous application at higher laminating temperatures and pressures. However, corrosion resistance and higher strength of stainless steel come at a price. Typically, 10 stainless steel sheet is even more expensive than copper and aluminum sheet.

The present invention provides a component for manufacturing printed circuit boards that has a copper foil protected by a metallic substrate, wherein the metallic substrate has the corrosion resistance of stainless steel at a significantly reduced cost.

#### Summary of the Invention

15       In accordance with the present invention, there is provided a component for use in manufacturing articles such as printed circuit boards. The component is comprised of a laminate constructed of a sheet of copper foil that, in a finished printed circuit board, constitutes a functional element, and a sheet of carbon steel having a layer of an inert metal thereon. The sheet of carbon steel constitutes a discardable 20 element. One surface of the copper sheet and the surface of the inert metal layer on the carbon steel sheet are essentially uncontaminated and are engageable with each other at interfaces. The copper sheet is attached to the inert metal layer of the carbon steel sheet at its borders to define substantially uncontaminated central zones inwardly of the edges.

25       In accordance with another aspect of the present invention, there is provided a sheet of copper foil for manufacturing multi-layer laminates comprising a sheet of copper foil having a thickness greater than about 5 microns. The copper foil has a first surface adapted for adhering to a fiber reinforced polymer layer, and a second surface to be exposed after the first surface is adhered to the fiber reinforced polymer layer. A 30 protective sheet of carbon steel having a thickness of about 0.05 mm to about 2.0 mm is provided. The carbon steel sheet has a layer of chromium with about 0.1 grams/m<sup>2</sup> to about 10 grams/m<sup>2</sup> electrodeposited on its surface. The layer of chromium engages

the second surface of the copper sheet and is attached thereto in a manner defining substantially uncontaminated central zones.

It is an object of the present invention to provide a component having a copper sheet for use in manufacturing articles, such as printed circuit boards, and a metallic substrate to protect a surface of the copper sheet before and during a manufacturing process.

It is a further object of the present invention to provide a component as described above wherein the metallic substrate is a relatively low cost, discardable item.

10 It is a further object of the present invention to provide a component as described above wherein the metallic substrate is formed of carbon steel and has an outer layer of an inert metal thereon for engagement with the copper sheet.

It is a further object of the present invention to provide a component as described above wherein the inert metal is chromium.

15 It is another object of the present invention to provide a component as described above that is suitable for high temperature processing applications.

A still further object of the present invention is to provide a component as described above wherein the discardable metallic substrate has a coefficient of thermal expansion approximately equal to the coefficient of thermal expansion of press plates used in forming laminated circuit boards.

20 A still further object of the present invention is to provide a component as described above wherein the metallic substrate is dimensioned and used as a press plate in a circuit board forming operation.

These and other objects will become apparent from the following description  
25 of a preferred embodiment taken together with the accompanying drawings and the appended claims.

#### Brief Description of the Drawings

The invention may take physical form in certain parts and arrangement of parts, a preferred embodiment of which will be described in detail in the specification  
30 and illustrated in the accompanying drawings which form a part hereof, and wherein:

FIG. 1 is an enlarged sectional view of a component used in forming articles such as printed circuit boards, illustrating a preferred embodiment of the present invention; and

FIG. 2 is a partially sectioned, top plan view of a portion of the component shown in FIG. 1.

Detailed Description of Preferred Embodiment

Referring now to the drawings wherein the showing is to illustrate a preferred embodiment of the invention only, and not for the purpose of limiting same, FIG. 1 shows a component 10 for use in manufacturing articles such as printed circuit boards, illustrating a preferred embodiment of the present invention. In the embodiment shown, component 10 is comprised of a metallic substrate, designated 12, having copper sheets, designated 20, attached thereto. Substrate 12 is comprised of a metallic sheet 14 having thin layers 16 of an inert metal formed on the surfaces thereof.

In accordance with a preferred embodiment of the present invention, metallic sheet 14 is comprised of conventional, mild carbon steel. Carbon steel sheet 14 preferably has a thickness of from about 0.05 mm to about 2.0 mm, and more preferably, has a thickness of from about 0.1 mm to about 0.3 mm. Layers 16 of inert metal on sheet 14 are preferably selected from the group consisting of nickel, copper, cobalt, brass, chromium, antimony, cadmium and combinations thereof. In a preferred embodiment of the present invention, layer 16 is comprised of essentially pure chromium. Chromium layer 16 preferably has a thickness of from about 0.1 gram/m<sup>2</sup> to about 10 grams/m<sup>2</sup>, and more preferably, has a thickness of from about 2.0 grams/m<sup>2</sup> to about 4.0 grams/m<sup>2</sup>. Chromium layer 16 may be deposited through a number of various conventionally known techniques, such as wet chemical deposition, autocatalytic deposition, chemical vapor deposition, e.g., evaporation or sputtering, ion bombardment or electrolytic deposition. In a preferred embodiment of the present invention, chromium layer 16 is electrolytically deposited on carbon steel sheet 14. In a preferred embodiment, carbon steel sheet 14 has a Rockwell 30-T hardness of between about 40 and about 60, a tensile strength of between about 390 newtons/mm<sup>2</sup> and about 440 newtons/mm<sup>2</sup>, a thickness of about 0.18 mm, and chromium layer 16 is about 2 grams/m<sup>2</sup>.

In accordance with the present invention, carbon steel sheet 14, with the chromium layers 16 thereon, has a width approximately equal to the width of copper sheets 20 to be attached thereto. Surface 22 of copper sheet 20 that is ultimately to be exposed and etched into a printed circuit is placed facing surface 18 of chromium layer 16 of carbon steel sheet 14. Surface 18 of chromium layer 16 is cleaned so as to

be substantially contamination-free. Copper foil sheets 20 are attached to chromium layer 16 of substrate 12 such that interior portions of the facing surfaces of sheets 20 are substantially uncontaminated in a region 30 inwardly from edge portions 32 of sheets 20. More specifically, copper sheets 20 are preferably attached to substrate 12 in the vicinity of edge portions 32 by an adhesive or an adhesive-like material (not shown). Such materials may include adhesives, resins or tapes. Copper sheets 20 may also be adhered by mechanical means, such as crimping, deforming and the like. In a preferred embodiment of the present invention, beads of a flexible adhesive (not shown), conventionally known in the art, are applied in edge portions 32 of copper sheets 20 and substrate 12 to secure the same to each other.

The present invention thus provides a component 10 for forming circuit boards or other articles that includes a copper sheet 20 adapted to be attached to a polymer board. Surface 22 of copper sheet 20 that is to be ultimately exposed and etched by a forming process is protected by a relatively inexpensive metallic substrate 12 having a thin layer 16 of an inert metal on an inner core 14 of carbon steel. The inert metal protects surface 22 of copper 20 from corrosion conventionally associated with ordinary carbon steel. At the same time, the carbon steel core 14 of metallic substrate 12 provides the strength of steel, at significantly less cost than using stainless steel sheet. Importantly, the carbon steel core 14 has essentially the same coefficient of thermal expansion as the press plates that conventional, multi-opening presses use in forming printed circuit boards. Thus, the laminated structure to be formed with copper sheet 20 is disposed between two materials having the same or similar coefficients of thermal expansion, i.e., the press plate and substrate 12. This provides a more uniform distribution of stresses in the laminate during the heating and compression steps of processing. In addition, the use of chromium as a protection layer on the steel allows for higher processing temperatures when using polymer materials requiring higher setting temperatures.

The foregoing description discloses preferred embodiments of the present invention. It should be appreciated that the embodiments are described for the purpose of illustration only, and that numerous alterations and modifications may be practiced by those skilled in the art without departing from the spirit and scope of the invention. It is intended that all such modifications and alterations be included insofar as they come within the scope of the invention as claimed or the equivalents thereof.

Having described the invention, the following is claimed:

1. A component for use in manufacturing articles, such as printed circuit boards, comprising: a laminate constructed of a sheet of copper foil that, in a finished printed circuit board, constitutes a functional element and a sheet of carbon steel having a layer of an inert metal thereon, said sheet of carbon steel constituting a discardable element, one surface of the copper sheet and the surface of the inert metal layer on the carbon steel sheet being essentially uncontaminated and engageable with each other at interfaces, said copper sheet being attached to the inert metal layer of the carbon steel sheet at its borders and defining a substantially uncontaminated central zones inwardly of the edges of the sheets and unjoined at the interfaces.
2. A component as defined in claim 1, wherein said inert metal is selected from the group consisting of nickel, copper, cobalt, brass, chromium, antimony and combination thereof.
3. A component as defined in claim 2, wherein said inert metal is chromium.
4. A component as defined in claim 3, wherein said chromium layer has a thickness of about 0.1 gram/m<sup>2</sup> to about 10 grams/m<sup>2</sup>.
5. A component as defined in claim 4, wherein said chromium layer has a thickness of about 2.0 grams/m<sup>2</sup> to about 4 grams/m<sup>2</sup>.
6. A component as defined in claim 3, wherein said chromium is electrolytically deposited on said carbon steel sheet.
7. A component as defined in claim 3, wherein said chromium is vapor deposited on said carbon steel sheet.
8. A component as defined in claim 1, wherein said carbon steel sheet has a thickness of about 0.05 mm to about 2.0 mm.
9. A component as defined in claim 4, wherein said carbon steel sheet has a thickness of about 0.1 mm to about 0.3 mm.
10. A component as defined in claim 1, wherein said copper sheet is attached to said inert metal layer by an adhesive along edges of said copper sheet and metal layer of said carbon steel sheet.
11. A protected sheet of copper foil for manufacturing multi-layer laminate, comprising:

(a) a sheet of copper foil having a thickness greater than about 5  $\mu\text{m}$  and having a first surface adapted for adhering to fiber reinforced polymer layer and a second surface to be exposed after said first surface is adhered to said fiber reinforced polymer layer;

(b) a protective sheet of carbon steel having a thickness of about 0.05 mm to about 2.0 mm, said carbon steel sheet having a layer of chromium of about 0.1 gram/m<sup>2</sup> to about 10 grams/m<sup>2</sup> electrodeposited thereon, said layer of chromium covering said second surface of said copper sheet and being attached thereto in a manner defining substantially uncontaminated central zones.

12. A sheet as defined in claim 11, wherein said copper sheet is attached to said carbon steel sheet along said layer of chromium by adhesive along edges of said sheets.

## 8

Abstract

A component for use in manufacturing articles, such as printed circuit boards, comprising a laminate constructed of a sheet of copper foil that, in a finished circuit board, constitutes a functional element, and a sheet of carbon steel having a layer of an inert metal thereon, the sheet of carbon steel constituting a discardable element. One surface of the copper sheet and the surface of the inert metal layer on the carbon steel sheet are essentially uncontaminated and engageable with each other at interfaces. The copper sheet is attached to the inert metal layer of the carbon steel sheet at their borders and defines substantially uncontaminated central zones inwardly of the edges of the sheets that are unjoined at the interfaces.

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FIGURE ONE

16L

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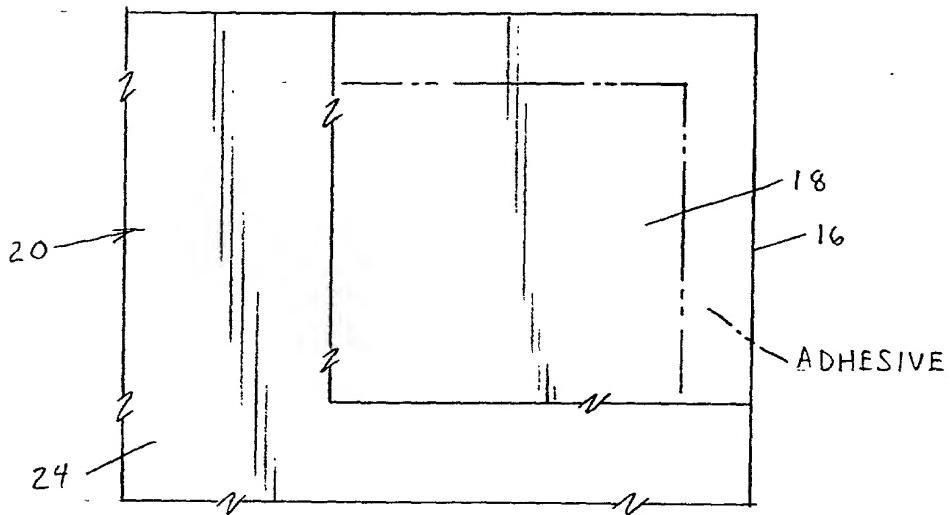


FIG. 2

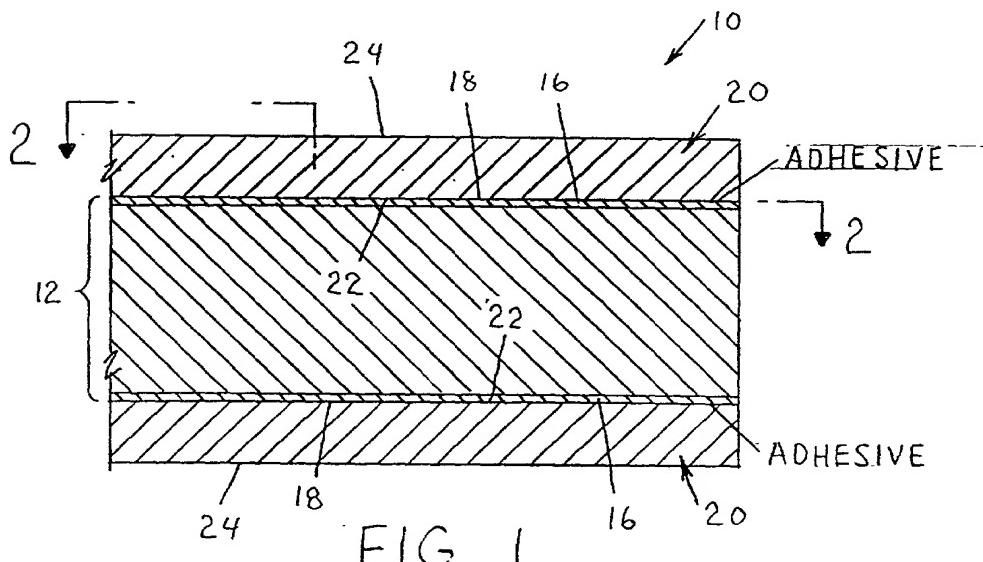


FIG. 1

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**COMBINED DECLARATION AND POWER OF ATTORNEY**

(ORIGINAL, DESIGN, NATIONAL STAGE OF PCT, SUPPLEMENTAL, DIVISIONAL,  
CONTINUATION, OR C-I-P)

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As a below named inventor, I hereby declare that:

**TYPE OF DECLARATION**

This declaration is for a national stage of PCT application.

**INVENTORSHIP IDENTIFICATION**

My residence, post office address and citizenship are as stated below, next to my name. I believe that I am the original, first and sole inventor (*if only one name is listed below*) or an original, first and joint inventor (*if plural names are listed below*) of the subject matter that is claimed, and for which a patent is sought on the invention entitled:

**TITLE OF INVENTION**

COMPONENT OF PRINTED CIRCUIT BOARDS

**SPECIFICATION IDENTIFICATION**

The specification was described and claimed in PCT International Application No. PCT/US98/23545 filed on November 4, 1998.

**ACKNOWLEDGMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR**

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information, which is material to patentability as defined in 37, Code of Federal Regulations, § 1.56, and which is material to the examination of this application, namely, information where there is a substantial likelihood that a reasonable Examiner would consider it important in deciding whether to allow the application to issue as a patent, and in compliance with this duty, there is attached an information disclosure statement, in accordance with 37 CFR 1.98.

**PRIORITY CLAIM (35 U.S.C. § 119(a)-(d))**

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s)

designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.

Such applications have been filed as follows.

**PRIOR PCT APPLICATION(S) FILED WITHIN 12 MONTHS  
(6 MONTHS FOR DESIGN) PRIOR TO THIS APPLICATION  
AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. § 119(a)-(d)**

INDICATE IF PCT	APPLICATION NUMBER	DATE OF FILING DAY, MONTH, YEAR	PRIORITY CLAIMED UNDER 35 USC 119
PCT	PCT/US98/23545	4/11/1998	yes

**POWER OF ATTORNEY**

I hereby appoint the following practitioner(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

Mark Kusner  
Michael A. Centanni

Registration Number 31,115 ✓  
Registration Number 34,796

I hereby appoint the practitioner(s) associated with the Customer Number provided below to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

---

SEND CORRESPONDENCE TO

DIRECT TELEPHONE CALLS TO:

Mark Kusner  
Mark Kusner Co., LPA  
Highland Place Suite 310  
6151 Wilson Mills Road  
Highland Heights, OH 44143

Mark Kusner  
(440) 684-1090

Customer Number 22203

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### DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

### SIGNATURE(S)

Bernd Schneider  
Inventor's signature  
Date 3/1/99  
Residence March-Holzhausen, DE  
Post Office Address

  
Dax  
Waldstrasse 17 a  
March-Holzhausen, 79232 DE

Country of Citizenship DE